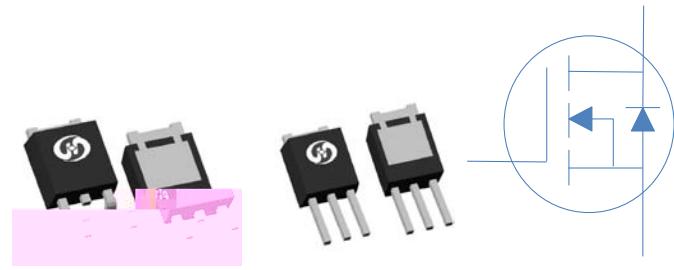


DS(on).typ		Ω
DS(on).typ		Ω



=25 (unless otherwise specified)

		=25		
		=100		
		=25		
Avalanche Energy, Single Pulse	E	=25		
Power Dissipation		=25		W
Operating and Storage Temperature				

Thermal Resistance Junction-Ambient	θ		W
Thermal Resistance Junction-Case	θ		W

Electrical Characteristics at T =25 (unless otherwise specified)
Static Characteristics

				typ
Drain to Source Breakdown Voltage		µ		
Gate Threshold Voltage	GS(th)	µ		
		=25		
		=100		µ
				Ω
	fs			
		Open, f=1MHz		Ω

Dynamic Characteristics

Input Capacitance		=30V, f=1MHz				pF
Output Capacitance						
Reverse Transfer Capacitance						
Total Gate Charge						
Total Gate Charge		Ω				
Gate to Source Charge						
Gate to Drain (Miller) Charge						
Turn off Delay Time	d(off)	Ω				
Fall Time	f					

Reverse Diode Characteristics

Diode Forward Voltage		F				
Reverse Recovery Charge		F	F/dt=300A/µ			



Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage



Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

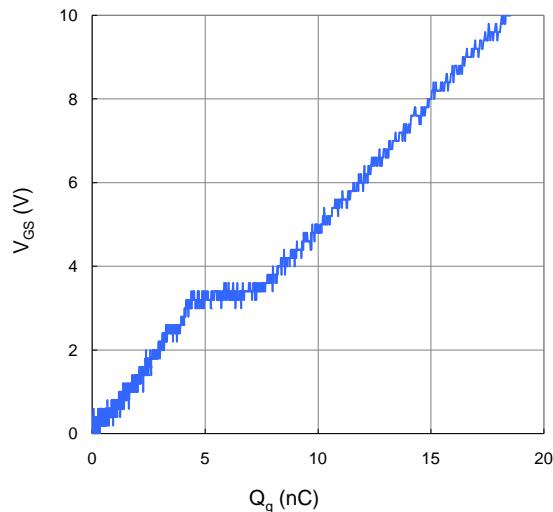


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

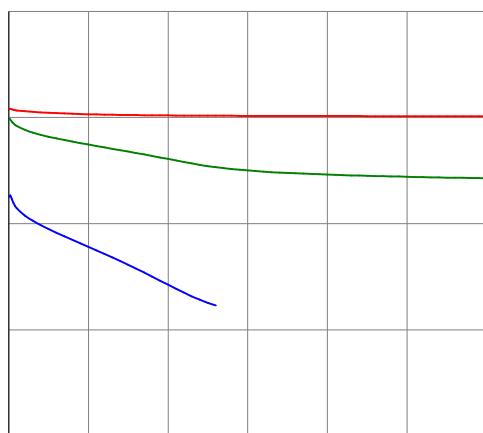


Figure 9. Maximum Safe Operating Area



Figure 10. Maximum Drain Current vs. Case Temperature

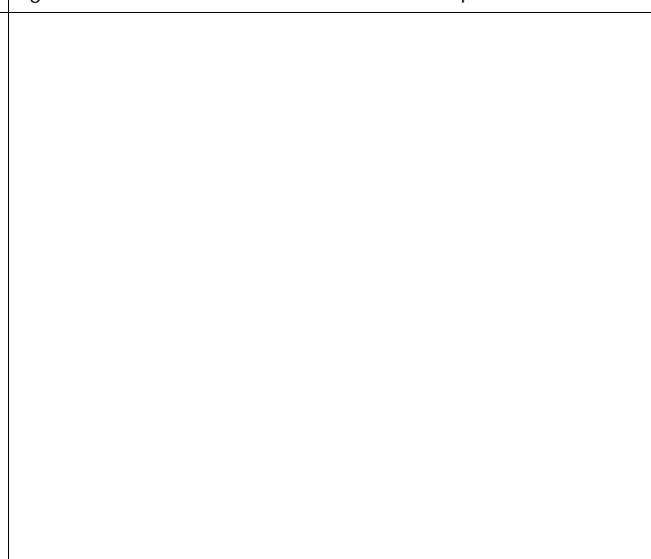
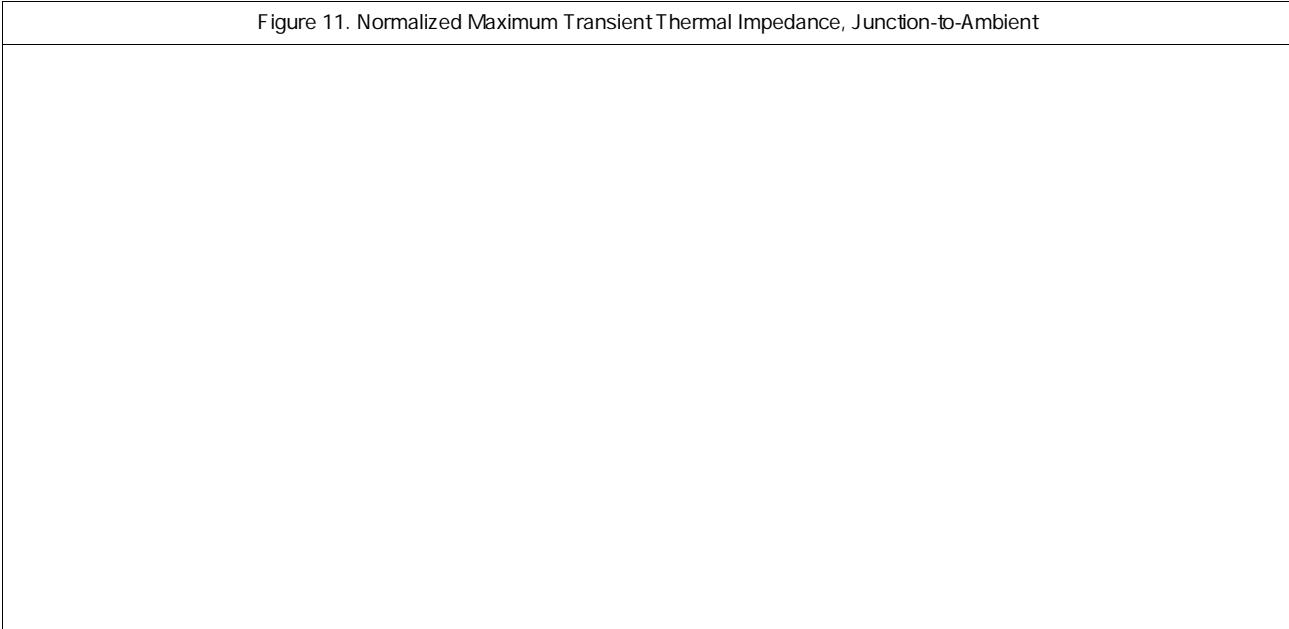
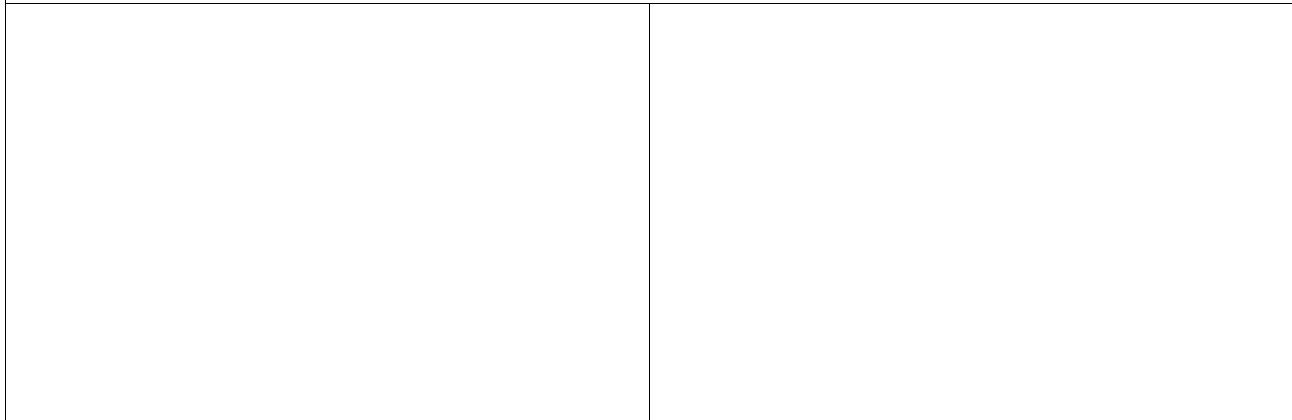


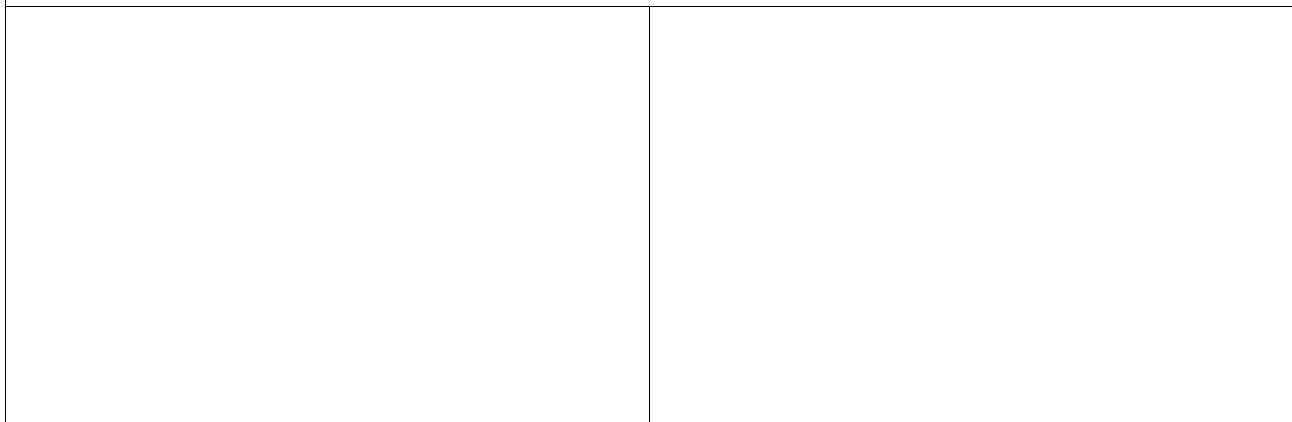
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



Inductive switching Test



Gate Charge Test



Uclamped Inductive Switching (UIS) Test

